

HD74HC688

8-bit Magnitude Comparator

REJ03D0643-0200
 (Previous ADE-205-529)
 Rev.2.00
 Mar 30, 2006

Description

The HD74HC688 compares bit for bit two 8-bit words and indicates whether or not they are equal. The $\overline{P=Q}$ output indicates equality when it is low.

A single active low enable is provided to facilitate cascading of several packages and enable comparison of words greater than 8-bits.

This device is useful in memory block decoding applications, where memory block enable signals must be generated from computer address information.

Features

- High Speed Operation: t_{pd} (P or Q to Output) = 17 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC688P	DILP-20 pin (JEDEC)	PRDP0020AC-B (DP-20NEV)	P	—
HD74HC688FPEL	SOP-20 pin (JEITA)	PRSP0020DD-B (FP-20DAV)	FP	EL (2,000 pcs/reel)
HD74HC688RPEL	SOP-20 pin (JEDEC)	PRSP0020DC-A (FP-20DBV)	RP	EL (1,000 pcs/reel)

Function Table

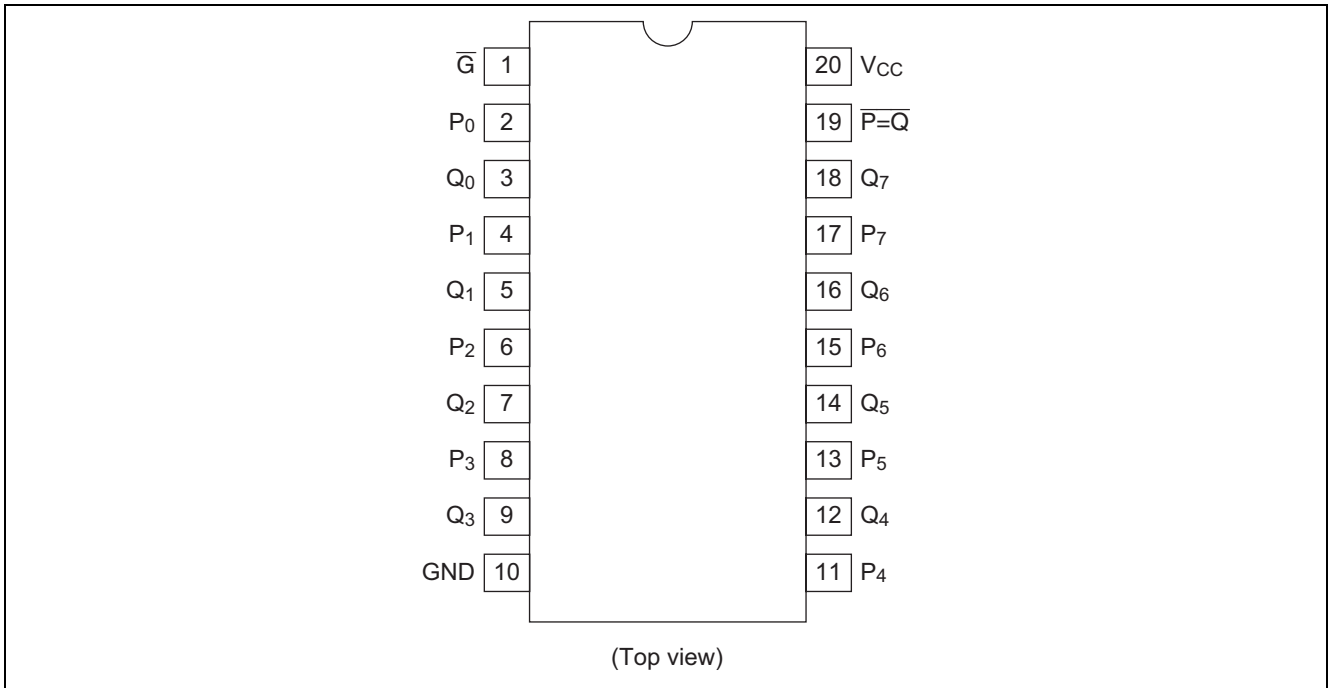
Input		Output $\overline{P=Q}$
Data P, Q	Enable \overline{G}	
P=Q	L	L
P>Q	L	H
P<Q	L	H
X	H	H

H : high level

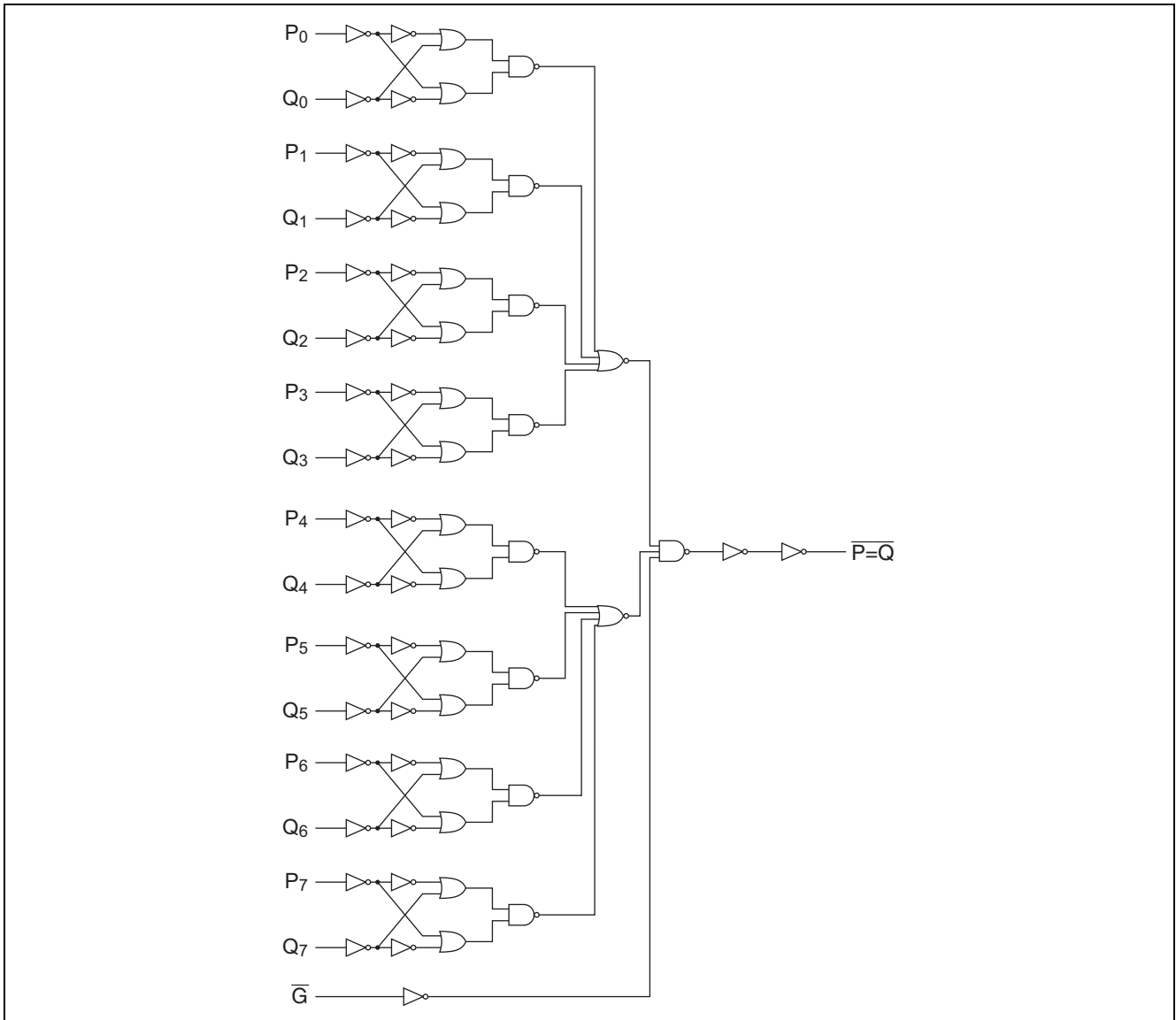
L : low level

X : irrelevant

Pin Arrangement



Logic Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
Input / Output voltage	V_{IN}, V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	I_{IK}, I_{OK}	± 20	mA
Output current	I_{OUT}	± 25	mA
V_{CC} , GND current	I_{CC} or I_{GND}	± 50	mA
Power dissipation	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	$^{\circ}C$

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V _{CC}	2 to 6	V	
Input / Output voltage	V _{IN} , V _{OUT}	0 to V _{CC}	V	
Operating temperature	T _a	-40 to 85	°C	
Input rise / fall time ^{*1}	t _r , t _f	0 to 1000	ns	V _{CC} = 2.0 V
		0 to 500		V _{CC} = 4.5 V
		0 to 400		V _{CC} = 6.0 V

Notes: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

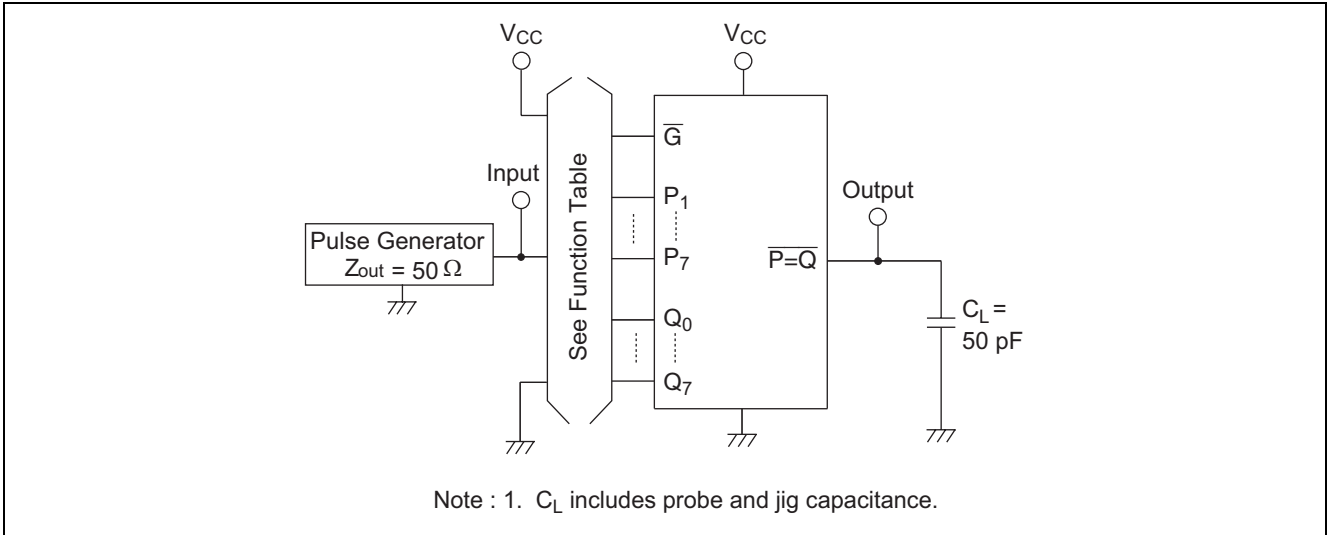
Item	Symbol	V _{CC} (V)	T _a = 25°C			T _a = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	V _{in} = V _{IH} or V _{IL}	I _{OH} = -20 μA
		4.5	4.4	4.5	—	4.4	—			I _{OH} = -4 mA
		6.0	5.9	6.0	—	5.9	—			I _{OH} = -5.2 mA
		4.5	4.18	—	—	4.13	—		I _{OL} = 20 μA	
		6.0	5.68	—	—	5.63	—			
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	V _{in} = V _{IH} or V _{IL}	I _{OL} = 20 μA
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	V _{in} = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	V _{in} = V _{CC} or GND, I _{out} = 0 μA	

Switching Characteristics

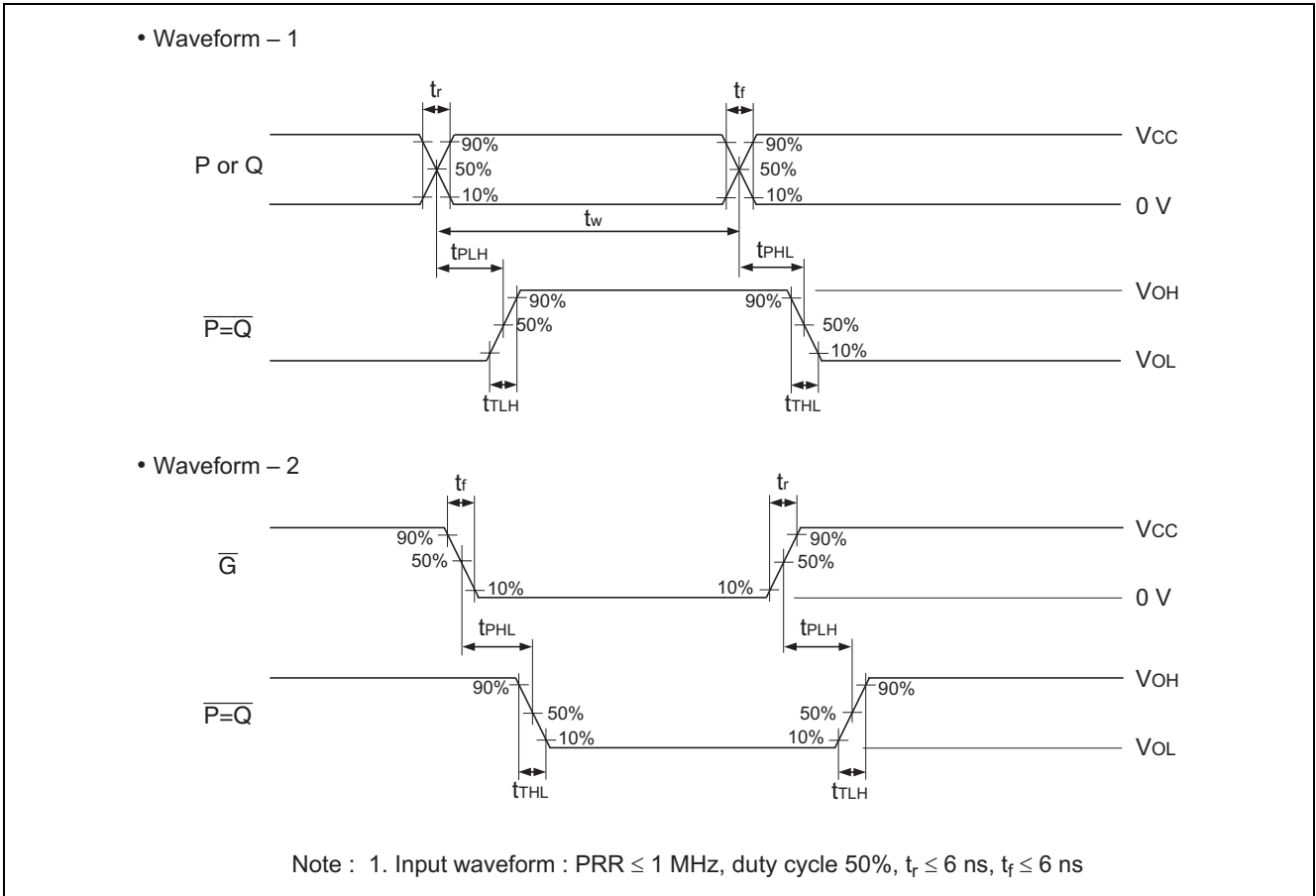
(C_L = 50 pF, Input t_r = t_f = 6 ns)

Item	Symbol	V _{CC} (V)	T _a = 25°C			T _a = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Propagation delay time	t _{PLH} t _{PHL}	2.0	—	—	210	—	265	ns	P or Q to output	
		4.5	—	17	42	—	53			
		6.0	—	—	36	—	45			
	t _{PLH} t _{PHL}	2.0	—	—	120	—	150	ns	Enable to P=Q	
		4.5	—	9	24	—	30			
		6.0	—	—	20	—	26			
Output rise/fall time	t _{TLH} t _{THL}	2.0	—	—	75	—	95	ns		
		4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Input capacitance	C _{in}	—	—	5	10	—	10	pF		

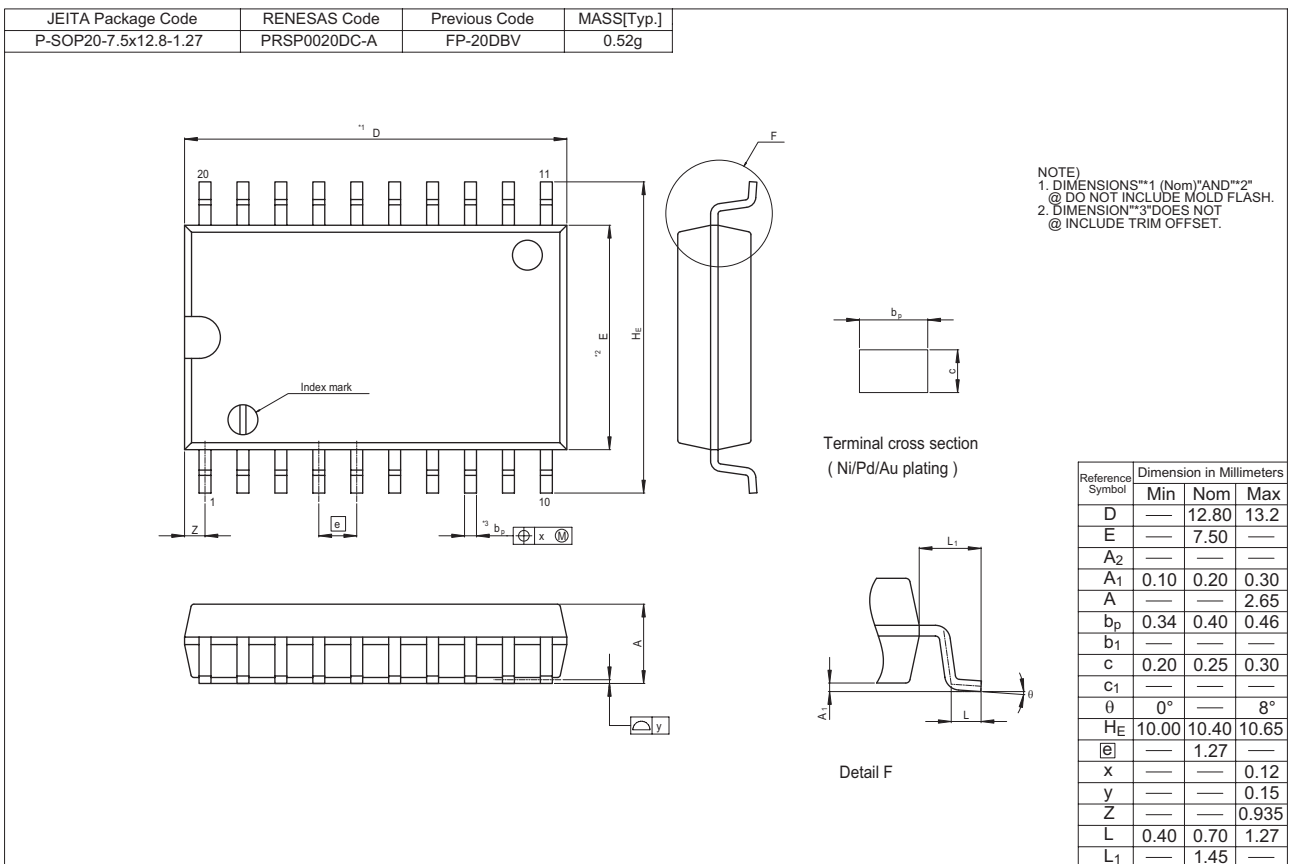
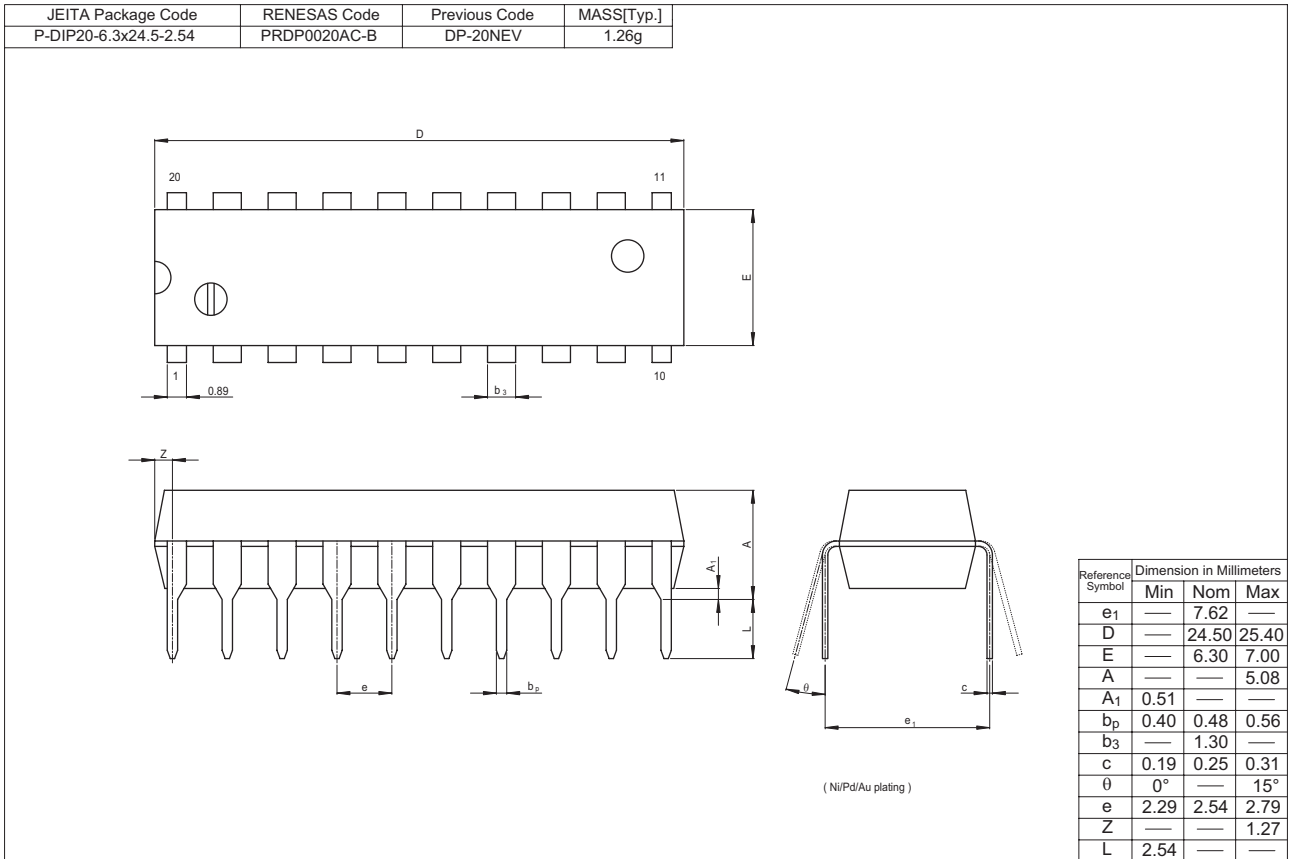
Test Circuit



Waveforms

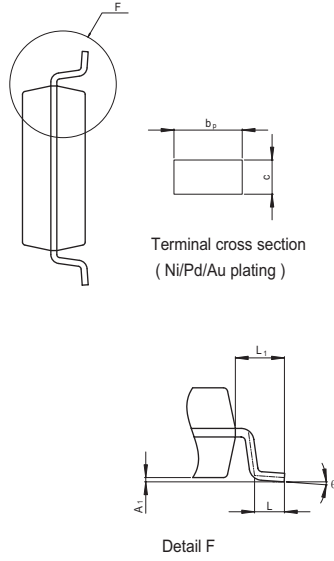
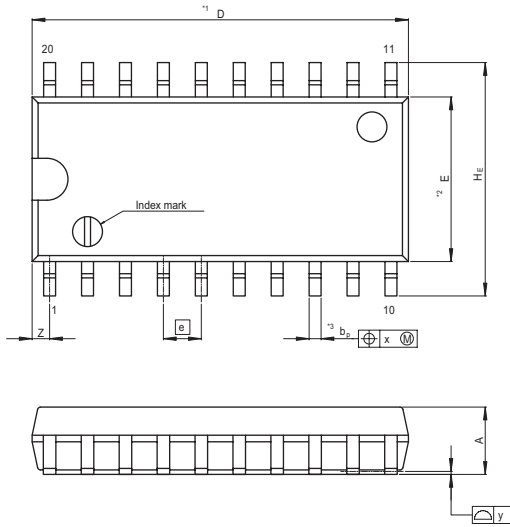


Package Dimensions



HD74HC688

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP20-5.5x12.6-1.27	PRSP0020DD-B	FP-20DAV	0.31g



NOTE
 1. DIMENSIONS**1 (Nom)**AND**2*
 DO NOT INCLUDE MOLD FLASH.
 2. DIMENSION**3*DOES NOT
 INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.60	13.0
E	—	5.50	—
A ₂	—	—	—
A ₁	0.00	0.10	0.20
A	—	—	2.20
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	7.50	7.80	8.00
ⓔ	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L ₁	—	1.15	—

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